

FDD5680

N-Channel, PowerTrench™ MOSFET

General Description

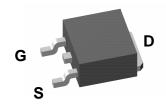
This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench process that has been especially tailored to minimize the on-state resistance and yet maintain low gate charge for superior switching performance.

Applications

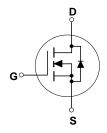
- DC/DC converter
- Motor drives

Features

- 38 A, 60 V. $R_{DS(on)} = 0.021~\Omega~@V_{GS} = 10~V$ $R_{DS(on)} = 0.025~\Omega~@V_{GS} = 6~V.$
- Low gate charge (33nC typical).
- Fast switching speed.
- High performance trench technology for extremely low R_{DS(on)}.



TO-252



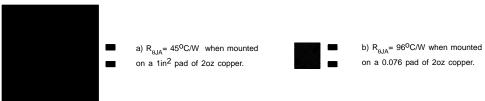
Symbol	Parameter		Ratings	Units
V_{DSS}	Drain-Source Voltage		60	V
V _{GSS}	Gate-Source Voltage		<u>±</u> 20	V
I _D	Maximun Drain Current - Continuous	(Note 1)	38	А
		(Note 1a)	8.5	
	Maximum Drain Current - Pulsed		100	
P _D	Maximum Power Dissipation @ T _C = 25°C	(Note 1)	60	W
	$T_A = 25^{\circ}C$	(Note 1a)	2.8	
	$T_A = 25^{\circ}C$	(Note 1b)	1.3	
T _J , T _{stq}	Operating and Storage Junction Temperature Range		-55 to +150	∘C

Thermal Characteristics				
$R_{\theta^{JC}}$	Thermal Resistance, Junction-to- Case	(Note 1)	2.1	°C/W
$R_{\theta^{JA}}$	Thermal Resistance, Junction-to- Ambient	(Note 1b)	96	°C/W
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Package Marking and Ordering Information				
Device Marking	Device	Reel Size	Tape width	Quantity
FDD5680	FDD5680	13"	16mm	2500

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	acteristics					
W _{DSS}	Single Pulse Drain-Source Avalanche Energy	$V_{DD} = 30 \text{ V}, I_{D} = 38 \text{ A}$			140	mJ
I _{AR}	Maximum Drain-Source Avalanche	e Current			38	Α
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	60			V
ΔBVnss ΔT,	Breakdown Voltage Temperature Coefficient	$I_D = 250\mu\text{A}$, Referenced to 25°C		60		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 48 V, V _{GS} = 0 V			1	μд
I _{GSSF}	Gate-Body Leakage Current, Forward	$V_{GS} = 20V, V_{DS} = 0 V$			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -20 \text{ V}, V_{DS} = 0 \text{ V}$			-100	nA
On Chara	acteristics (Note 2)					
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	2	2.4	4	V
$\Delta V_{GS(th)} = \Delta T_{,J}$	Gate Threshold Voltage Temperature Coefficient	$I_D = 250 \mu\text{A}, \text{Referenced to } 25^{\circ}\text{C}$		-6.4		mV/°C
$R_{\text{DS(on)}}$	Static Drain-Source On-Resistance	$V_{GS} = 10 \text{ V}, I_D = 8.5 \text{ A}$ $V_{GS} = 10 \text{ V}, I_D = 8.5 \text{ A}, T_J = 125^{\circ}\text{C}$ $V_{GS} = 6 \text{ V}, I_D = 7.5 \text{ A}$		0.017 0.028 0.019	0.021 0.042 0.025	Ω
I _{D(on)}	On-State Drain Current	V _{GS} = 10 V, V _{DS} = 5 V	50			Α
g _{FS}	Forward Transconductance	$V_{DS} = 5 \text{ V}, I_{D} = 8.5 \text{ A}$		30		S
Dvnamic	Characteristics					
C _{iss}	Input Capacitance	V _{DS} = 30 V, V _{GS} = 0 V,		1835		pF
C _{oss}	Output Capacitance	f = 1.0 MHz		210		pF
C _{rss}	Reverse Transfer Capacitance			90		pF
Switchin	g Characteristics (Note 2)					
t _{d(on)}	Turn-On Delay Time	$V_{DD} = 30 \text{ V}, I_{D} = 1 \text{ A},$		15	27	ns
t _r	Turn-On Rise Time	V_{GS} = 10 V, R_{GEN} = 6 Ω		9	18	ns
t _{d(off)}	Turn-Off Delay Time			35	56	ns
t _f	Turn-Off Fall Time			16	26	ns
Q_g	Total Gate Charge	$V_{DS} = 30 \text{ V}, I_{D} = 8.5 \text{ A},$		33	46	nC
Q _{gs}	Gate-Source Charge	V _{GS} = 10 V,		6.5		nC
Q _{gd}	Gate-Drain Charge			7.5		nC
Drain-So	urce Diode Characteristics	and Maximum Ratings				
I _S	Maximum Continuous Drain-Source				2.3	Α
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 2.3 A (Note 2)		0.75	1.2	V

^{1.} $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient resistance where the case thermal reference is defined as the drain tab. $R_{\theta JC}$ is guaranteed by design while $R_{\theta JA}$ is determined by the user's board design.



Scale 1 : 1 on letter size paper

^{2.} Pulse Test: Pulse Width $\leq 300~\mu s$, Duty Cycle $\leq 2.0\%$

Typical Characteristics

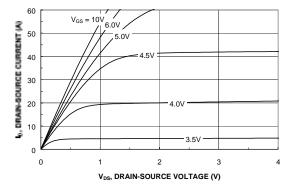


Figure 1. On-Region Characteristics.

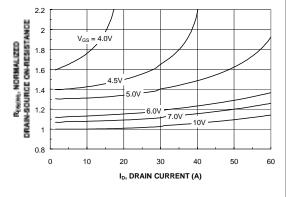


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

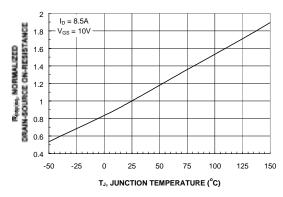


Figure 3. On-Resistance Variation with Temperature.

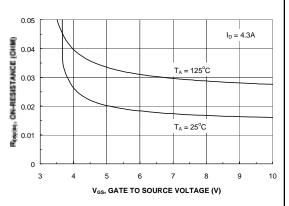


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

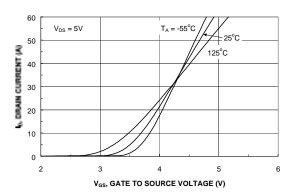


Figure 5. Transfer Characteristics.

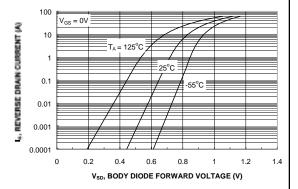
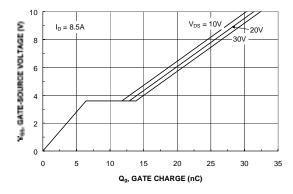


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics (continued)



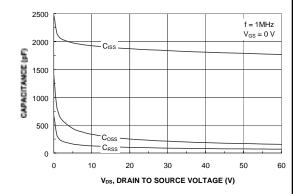
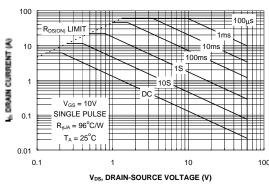


Figure 7. Gate-Charge Characteristics.

Figure 8. Capacitance Characteristics.



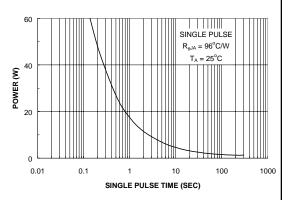


Figure 9. Maximum Safe Operating Area.

Figure 10. Single Pulse Maximum Power Dissipation.

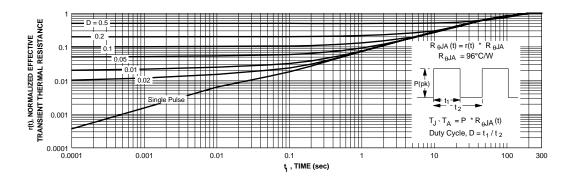


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1b. Transient themal response will change depending on the circuit board design.

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